



Material Content Data Sheet



Sales Product Name		BTF3080EJ		Issued		9. January 2019		
MA#		MA002843816						
Package		PG-TDSO-8-31		Weight*		67.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.592	2.36	2.36	23598	23598
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		563	
	non noble metal	iron	7439-89-6	0.760	1.13		11259	
wire	non noble metal	copper	7440-50-8	30.851	45.72	46.92	457155	469118
	non noble metal	copper	7440-50-8	0.323	0.48	0.48	4791	4791
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.14		1422
plastics		epoxy resin	-	3.742	5.54		55447	
	inorganic material	silicondioxide	60676-86-0	28.144	41.70	47.38	417039	473908
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7368	7368
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12222	12222
glue	plastics	epoxy resin	-	0.106	0.16		1574	
	noble metal	silver	7440-22-4	0.501	0.74	0.90	7421	8995
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com